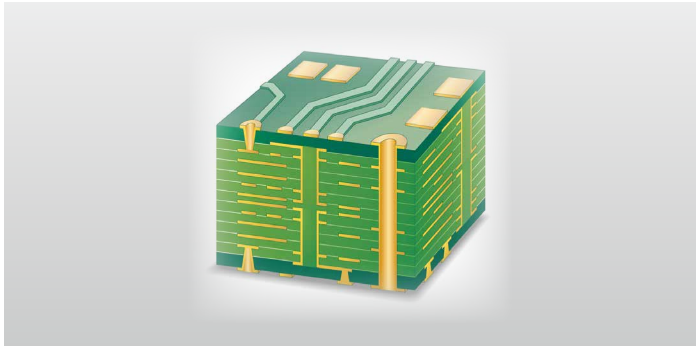
KYOCERA

HIGH-DENSITY MULTILAYER PWBS



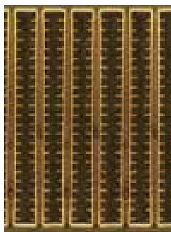
APPLICATIONS

- Servers
- High performance network equipment and multiple equipment
- Base Transceiver Stations (BTS)
- Measuring devices

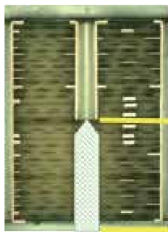
FEATURES

- High-precision, ultra-fine lines/spaces and high aspect ratio via holes
- Flexibility of design because of sequential lamination
- Back drill, stack via, skip via and accurate impedance control for high speed signal
- Up to 210 µm thick copper supports supply of large current

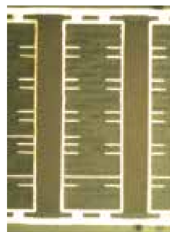
VARIOUS MANUFACTURING TECHNOLOGIES FOR HIGH-DENSITY MULTILAYER PWBS



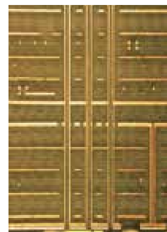
High aspect ratio hole drilling technology



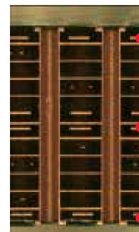
Back drill technology



HDI Technology



Sequential lamination technology



BC (Buried Capacitance)

BC (Buried Capacitance)

BC (Buried Capacitance)

Processing buried capacitance technology

STANDARD DESIGN SPECIFICATIONS

Item		Specifications
Layer of build-up (max.)		3
L/S (Min.)	Inner layer	75/75 µm
L/S (Min.)	Outer layer	75/75 µm

Item		Specifications
Via hole/ Via land	(LVH)	100/250 µm
Via hole/ Via land	(IVH)	250/550 µm
Via hole/ Via land	(Plated through hole)	250/550 µm

Item	Specifications
Count of layer (max.)	50
Board thickness (max.)	7.0 mm
Aspect ratio (max.)	25

Special specifications or fine specifications over standard design specifications available on enquiry.

KYOCERA Europe GmbH · Fritz-Mueller-Strasse 27 · 73730 Esslingen / Germany
Tel.: +49 (0)711 - 93 93 4-0 · E-Mail: info@kyocera.de · www.kyocera.eu

© 2020 KYOCERA Europe GmbH. We reserve the right to make changes without prior notice.